




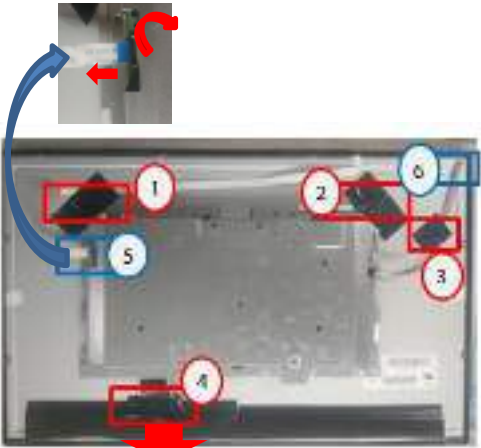
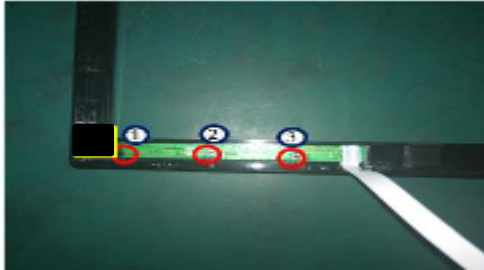

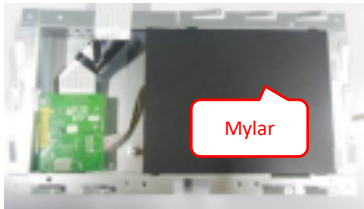

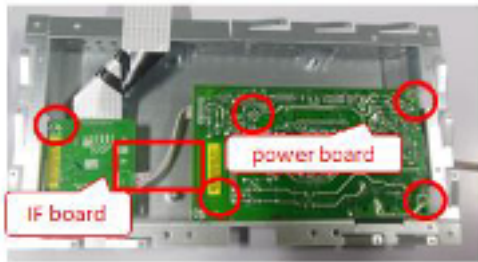
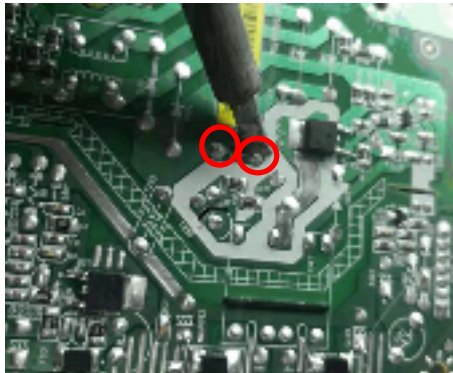


DELL E-Series (Applicable for EXX16, EXX18)

1. Disassemble Procedures

S1	Turn off power	S4	<p>Use Philips-head screwdriver ($\Phi 5$ mm) to remove 4 screws for unlocking. 1-4 screw size M4 x 10, Torque = 11 to 13Kgf.cm <i>*For VGA connectivity, use Hexagonal screwdriver to remove 2 VGA screws. Torque = 0.8 +/- 0.1Kgf.cm</i></p> 
S2	Unplug cables from monitor 	S5	<p>Turn the monitor (panel face up), disassemble front bezel start from top of monitor.</p> 
S3	Remove stand from monitor release button (with Philip-head screwdriver) 	S6	<p>After front bezel completely removed, turn the monitor (panel face down) and remove the back cover.</p> 

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S7	<p>Remove 4 black tape Remove cables: Keypad cable (5) and Backlight Cable (6)</p> 	<p>S10</p> <p>Use Philips-head screwdriver (Φ3 mm) to remove 3 screws from Keypad board T2 *3. Torque: 1.0 +/- 0.1Kgf.cm</p> 
S8	<p>Remove LVDS Cable from panel</p>  <p>Flip the chassis and remove Mylar</p> 	<p>S11</p> <p>Remove electrolyte capacitor >25mm height (red mark) from printed circuit boards. Cut the glue between bulk cap and PCBA with knife – ensure cutting path within the glue, don't touch bulk cap and PCBA.</p> 
S9	<p>Remove 4 Power Board screws with Philip-head screwdriver (Φ5 mm) Remove IF board 1 screw with Philip-head screwdriver. (VGA & DP connectivity *2 screws). M3 x 6, Torque = 5.5 kgf +/-0.5 kgf Remove cables from IF & power board.</p> 	<p>S12</p> <p>Take out the capacitor pin solder with soldering iron. Lift the bulk capacitor away from power board.</p> 

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2. Product Material Information

The following substances, preparation, or components should be disposed of or recovered separately from other WEEE in compliance with Article 4 of EU Council Directive 75/422/EEC.

Capacitors / Condensers (containing PCB/PCT)	Not used
Mercury containing components	Not used
Batteries	Not used
Printed circuit boards (with surface greater than 10 square cm)	Product has printed circuit boards (with surface greater than 10 square cm)
Component contain toner, ink and liquids	Not used
Plastic containing BFR	
Component and waste contain asbestos	Not used
CRT	Not used
Component contain CFC, HCFC, HGC and HC	Not used
Gas discharge lamps	Not use
LCD display > 100 cm ²	Product LCD greater than 100cm ²
External electric cable	Product has external cables
Component contain refractory ceramic fibers	Not used
Component contains radio-active substances	Not used
Electrolyte capacitors (height > 25mm, diameter >25mm)	Product has electrolyte capacitors (height > 25mm)

3. Tools Required

List the type and size of the tools that would typically can be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description:-

- Screwdriver (Philip head with Ø5 mm & Ø3 mm)
- Screwdriver (Hexgonal to remove VGA connectivity)
- Soldering iron
- Knife